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Application No.: 10/755,042

Docket No.: JCLA8533-D2

## AMENDMENTS

### In The Claims:

Please amend the claims as indicated hereafter.

#### **Claims 1-162. (canceled)**

163. (new) An electronic package comprising:  
a substrate comprising silicon;  
a die joined with said substrate; and  
an upper metallization structure over said die and extending to a place not over said die,  
wherein said upper metallization structure comprises an electroplated metal.

164. (new) The electronic package in claim 163, wherein a cavity is in said substrate and accommodates said die, said die having a bottom surface joined with the bottom of said cavity.

165. (new) The electronic package in claim 163, wherein said substrate has a top surface comprising a first region and a second region, said die joined with said first region, said second region not covered by said die, said first region being coplanar with said second region.

166. (new) The electronic package in claim 163, wherein an opening is in said substrate and accommodates said die, said substrate having a top surface coplanar with a top surface of said die, and a bottom surface coplanar with a bottom surface of said die.

Page 2 of 15

Application No.: 10/755,042

Docket No.: JCLA8533-D2

167. (new) The electronic package in claim 163 further comprising a polymer layer under a metal layer of said upper metallization structure.

168. (new) The electronic package in claim 163 further comprising a polymer layer over a metal layer of said upper metallization structure.

169. (new) The electronic package in claim 163, wherein said die has a top surface at a horizontal level, said substrate being under said horizontal level, said upper metallization structure being over said horizontal level.

170. (new) The electronic package in claim 169, wherein said top surface comprises multiple pads.

171. (new) The electronic package in claim 169 further comprising a passive device over said horizontal level.

172. (new) The electronic package in claim 163 further comprising an adhesive tape joining said die and said substrate.

173. (new) The electronic package in claim 163 further comprising an conductive paste joining said die and said substrate.

Application No.: 10/755,042

Docket No.: JCLA8533-D2

174. (new) The electronic package in claim 163 further comprising a bump on a pad of said upper metallization structure, wherein said bump comprises solder.

175. (new) The electronic package in claim 163 further comprising a bump on a pad of said upper metallization structure, wherein said bump comprises gold.

176. (new) The electronic package in claim 163 further comprising a fillinglayer over said substrate and surrounding said die.

177. (new) The electronic package in claim 177, wherein said filling layer comprises polymer.

178. (new) The electronic package in claim 177, wherein said filling layer comprises epoxy.

179. (new) An electronic package comprising:  
a substrate comprising silicon;  
a die joined with said substrate and comprising multiple internal circuits; and  
an upper metallization structure over said die and extending to a place not over said die, wherein said upper metallization structure comprises a portion connecting said multiple internal circuits.

Application No.: 10/755,042

Docket No.: JCLA8533-D2

180. (new) The electronic package in claim 179, wherein a cavity is in said substrate and accommodates said die, said die having a bottom surface joined with the bottom of said cavity.

181. (new) The electronic package in claim 179, wherein said substrate has a top surface comprising a first region and a second region, said die joined with said first region, said second region not covered by said die, said first region being coplanar with said second region.

182. (new) The electronic package in claim 179, wherein an opening is in said substrate and accommodates said die, said substrate having a top surface coplanar with a top surface of said die, and a bottom surface coplanar with a bottom surface of said die.

183. (new) The electronic package in claim 179 further comprising a polymer layer under a metal layer of said upper metallization structure.

184. (new) The electronic package in claim 179 further comprising a polymer layer over a metal layer of said upper metallization structure.

185. (new) The electronic package in claim 179, wherein said portion is used to transmit a signal.

186. (new) The electronic package in claim 179, wherein said portion is used to provide a power voltage.

Application No.: 10/755,042

Docket No.: JCLA8533-D2

187. (new) The electronic package in claim 179, wherein said portion is used to provide a ground voltage.

188. (new) The electronic package in claim 179, wherein said die has a top surface at a horizontal level, said substrate being under said horizontal level, said upper metallization structure being over said horizontal level.

189. (new) The electronic package in claim 188, wherein said top surface comprises multiple pads.

190. (new) The electronic package in claim 188 further comprising a passive device over said horizontal level.

191. (new) The electronic package in claim 179 further comprising an adhesive tape joining said die and said substrate.

192. (new) The electronic package in claim 179 further comprising an a conductive paste joining said die and said substrate.

193. (new) The electronic package in claim 179 further comprising a bump on a pad of said upper metallization structure, wherein said bump comprises solder.

Application No.: 10/755,042

Docket No.: JCLA8533-D2

194. (new) The electronic package in claim 179 further comprising a bump on a pad of said upper metallization structure, wherein said bump comprises gold.

195. (new) The electronic package in claim 179 further comprising a film layer over said substrate and surrounding said die.

196. (new) The electronic package in claim 179, wherein said filling layer comprises polymer.

197. (new) An electronic component comprising:  
a die comprising multiple internal circuits; and  
an upper metallization structure over said die and extending to a place not over said die, wherein said upper metallization structure comprises a portion connecting said multiple internal circuits and used to provide a ground voltage.

198. (new) The electronic component in claim 197 further comprising a substrate joined with said die.

199. (new) The electronic component in claim 198, wherein said substrate comprises silicon.

Application No.: 10/755,042

Docket No.: JCLA8533-D2

200. (new) The electronic component in claim 198, wherein a cavity is in said substrate and accommodates said die, said die having a bottom surface joined with the bottom of said cavity.

201. (new) The electronic component in claim 198, wherein said substrate has a top surface comprising a first region and a second region, said die joined with said first region, said second region not covered by said die, said first region being coplanar with said second region.

202. (new) The electronic component in claim 197 further comprising a polymer layer under a metal layer of said upper metallization structure.

203. (new) The electronic component in claim 197 further comprising a polymer layer over a metal layer of said upper metallization structure.

204. (new) The electronic component in claim 197 further comprising a film layer, wherein an opening is in said film layer and accommodate said die, said film layer having a top surface coplanar with a top surface of said die, and a bottom surface coplanar with a bottom surface of said die.

205. (new) The electronic component in claim 197, wherein said film layer comprises polymer.

**Application No.: 10/755,042**

**Docket No.: JCLA8533-D2**

206. (new) The electronic component in claim 197, wherein said portion is a bus shape.

207. (new) The electronic component in claim 197, wherein said upper metallization structure is over a top surface of said die, said top surface of said die comprising multiple pads.

208. (new) The electronic component in claim 197 further comprising a passive device connected to said die through said upper metallization structure.